

Part Number: **SBGxxxCT-13-F**
Weight (mg): 1700

XXX= 1030, 1035, 1040, 1045, 1630, 1635, 1640,
1645, 2030, 2035, 2040, 2045, 3030, 3040,
3045, 3050, 3060

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	0.60	10.20	1000000	6000
Leadframe	Copper Alloy	Cu	7440-50-8	97.45%	54.66	929.22	974500	532662
		Fe	7439-89-6	2.40%			24000	13118
		P	7723-14-0	0.03%			300	164
		Zn	7440-66-6	0.12%			1200	656
Die Attach Solder	RoHS Exempt High Temperature	Lead	7439-92-1	92.50%	0.50	8.50	925000	4625
		Sn	7440-31-5	5.00%			50000	250
		Silver	7440-22-4	2.50%			25000	125
Encapsulation	EME-1200	Silica (SiO ₂) (60-90%)	14808-60-7	75.00%	43.24	735.08	750000	324300
		epoxy resin	29690-82-2	13.50%			135000	58374
		Phenol-formaldehyde polymer (5-10%)	9003-35-4	7.50%			75000	32430
		TBBA-diglycidyl-ether oligomer (1-2%)	40039-93-8	1.50%			15000	6486
		Sb ₂ O ₃ (0-5%)	1309-64-4	2.50%			25000	10810
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.00	17.00	1000000	10000
				Total	100.00	1700.00		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |